

1/2

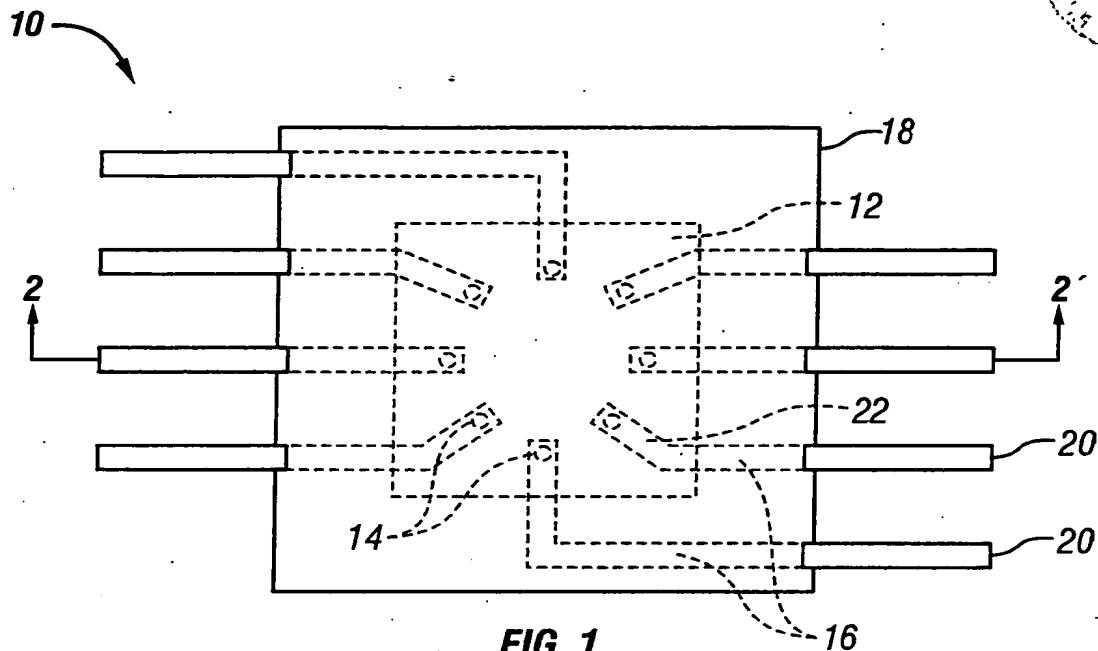


FIG. 1

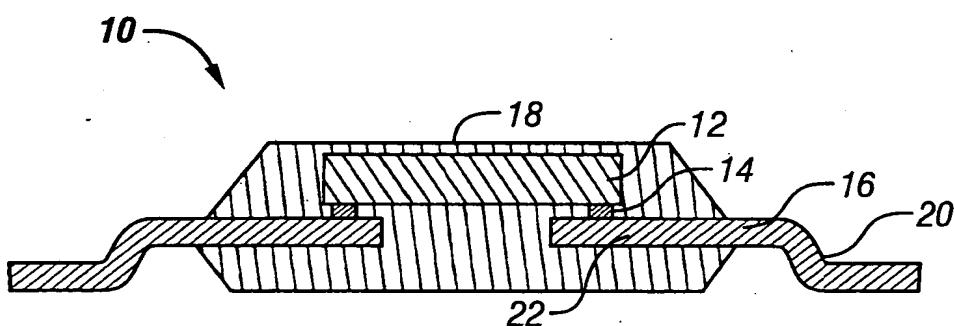


FIG. 2

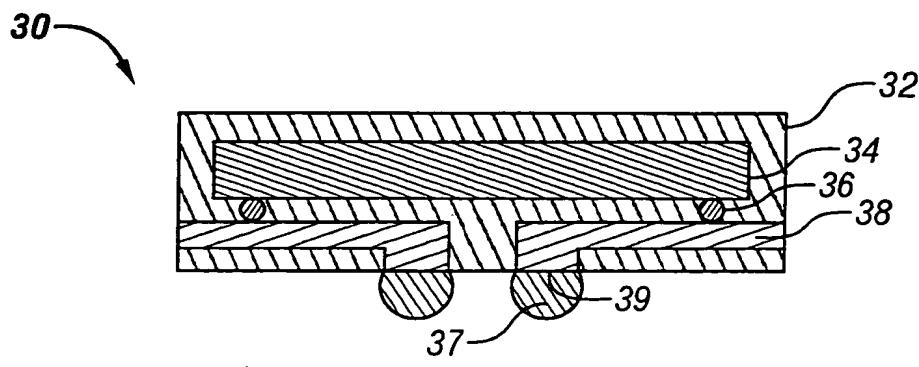


FIG. 3

Title: **Flip chip-in-leadframe package and process**

Inventor: PENDSE, *et al.*
USSN: 09/802,443

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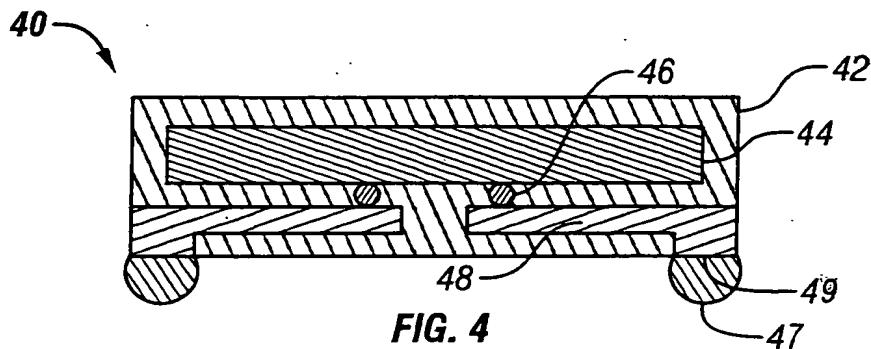


FIG. 4

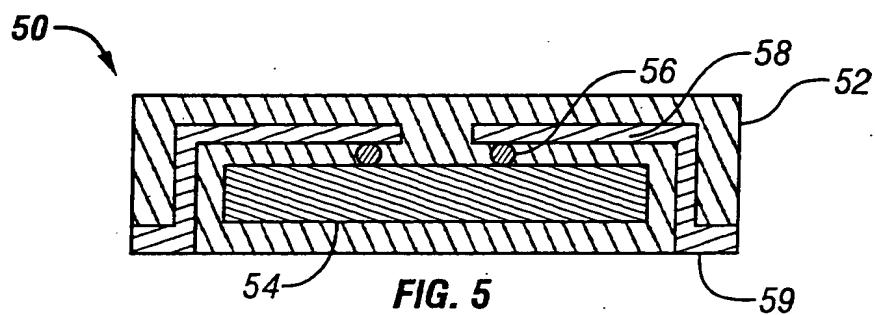


FIG. 5

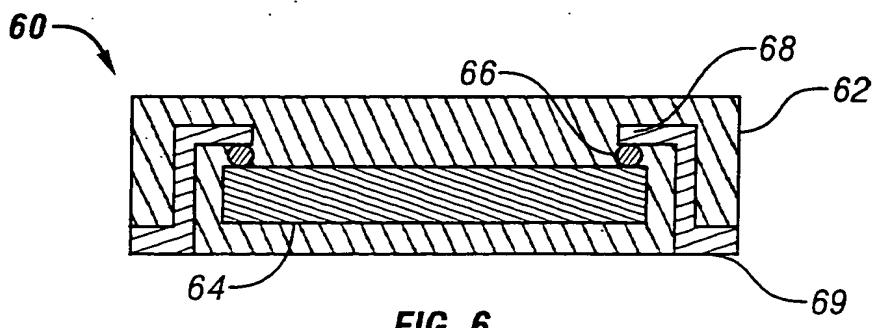


FIG. 6